

CCK13-16/90

SUBRACK

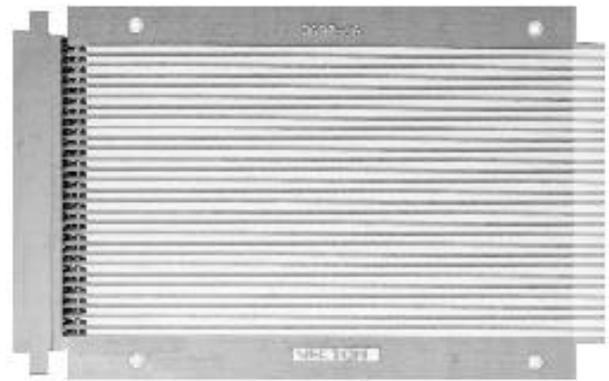
3U Subrack with 16-slot backplane
(photo)

3U Subrack with 8 slot backplane
(CCK13-HT8/90)

EXTENDER BOARD

STD 3690-16

- Length:** 6.5" (165.1mm)
- Height:** 4.5" (114.3mm)
- Contacts:** 56 @ .125" Ctrs Ni/Gold
- Current Rating:** 5 amps at 10° F. rise
- Voltage Rating:** 200 RMS or 300 VDC
- Material:** FR4 Epoxy Glass 2 oz. Cu.

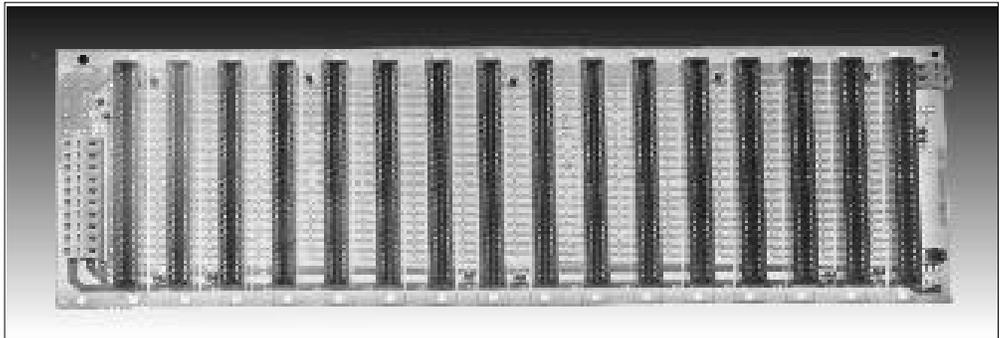


8 and 16-slot

Fully assembled and tested, Vector Backplanes for STD Bus applications. 8 or 16-slot versions available, connector spacing is on 0.75" centers. Ample positions for decoupling capacitors. Meets all STD Bus specifications, including interrupt priority lines. Featuring:

- Faraday shield lines reduce cross-talk
- Wiring pads on board to connect RESET switch for front panel controls
- High reliability connectors with gold/plated contacts and 10-position power connector
- Wago power blocks

BACKPLANES



Specifications:

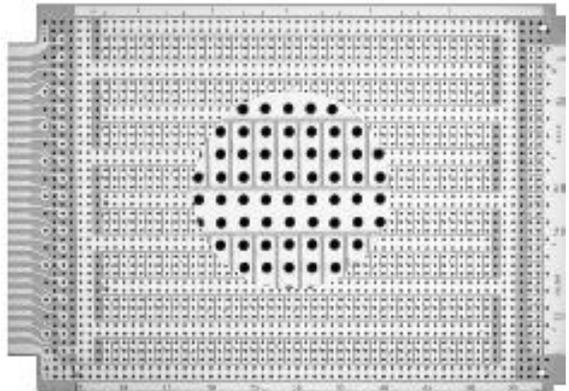
- Material:** FR4 Epoxy Glass. .093" thick, UL94-V-0 compliant
- Operating Temp.:** 0 to 60°C
- Storage:** -20 to 60°C
- Rel. Humidity:** 0-95%, non condensing

Part No.	Description	Dimensions			Connector Spacing	Accessories		
		Width	Length	Thickness		Plugboard Series	Extender	Card Racks/Enclosure
4610-8-1A	8-slot assembled	4.35"	7.00"	1/16"	.750"	4610 Series	3690-16	CCK 13 Series
4610-16-1A	16-slot assembled	4.35"	13.00"	1/16"	.750"	4610 Series	3690-16	CCK 13 Series

Other Buses

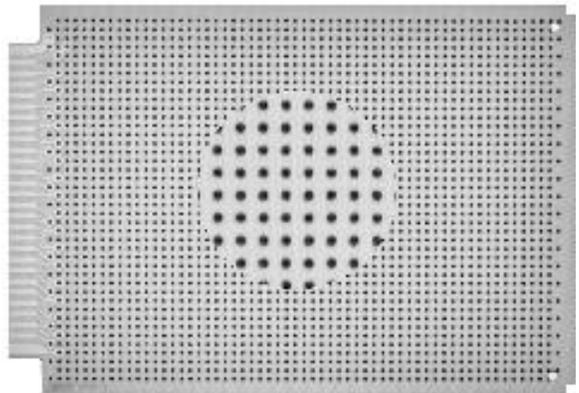
4610 STD

Circuit Pattern: 3-Hole Solder Pad
Contacts: 28/56 @ .125" Ctrs, • I/O mounting area for ribbon cable header
 Ni/Gold
Width/Thick: 6.5"/.062" • Solder pads on wiring side: component side has contacts only
Height: 4.5" • Layout paper and instructions included
16-Pin DIP Capacity: 20 • Pad and bus surfaces solder-coated for user convenience
Material: CEM-1
V/G Terminals: T44, T46, T49, T68
Wire-Wrap Socket Pins: R32
Extender: 3690-16
Solder Connector: R656-1
Wire-Wrap Connector: R656
Rec. Card Cage: Series 13
Hole Diameter: .042"



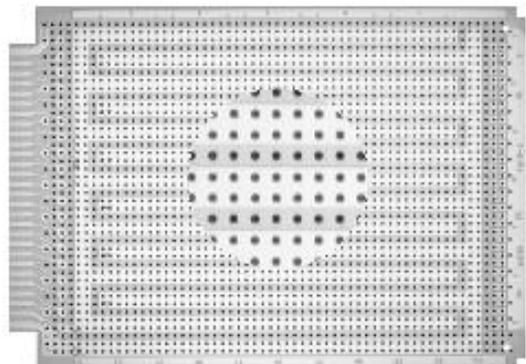
4610-1 STD

Circuit Pattern: Contacts Only
Contacts: 28/56 @ .125" Ctrs, Ni/Gold
Width/Thick: 6.5"/.062" • Unrestricted component placement over entire board surface
Height: 4.5" • Layout paper and instructions included
16-Pin DIP Capacity: 59
Material: CEM-1
Wire-Wrap Terminals: T44, T46, T49, T68
Wire-Wrap Socket Pins: R32
Solder Connector: R656-1
Extender: 3690-16
Rec. Card Cage: Series 13
Wire-Wrap Connector: R656
Hole Diameter: .042"



4610-2 STD

Circuit Pattern: Interleaved Buses
Contacts: 28/56 @ .125" Ctrs, Ni/Gold
Width/Thick: 9.6"/.062" • Power and ground buses on wiring side only, component side has contacts only
Height: 4.5" • I/O mounting area for ribbon cable connector
16-Pin DIP Capacity: 35 • Layout paper and instructions included
Material: CEM-1
Wire-Wrap Terminals: T44, T46, T49, T68
Wire-Wrap Socket Pins: R32
Solder Connector: R656-1
Extender: 3690-16
Rec. Card Cage: Series 13
Wire-Wrap Connector: R656
Hole Diameter: .042"



4610-3 STD

Circuit Pattern: Pad-Per-Hole
Contacts: 28/56 @ .125" Ctrs Ni/Gold
Width/Thick: 6.5"/.062" • Layout paper and instructions included
Height: 4.5" w • Row and column legends provided
16-Pin DIP Capacity: 52 • 0.042" plated -thru holes on on 0.1" grid
Material: FR4 Epoxy Glass
V/G Terminals: T44, T46, T49, T68
Socket Pins: R32
Solder Connector: R656-1
Extender: 3690-16
Rec. Card Cage: Series 13
Wire-Wrap Connector: R656
Hole Diameter: .042"

